LAUNCHING LLS2500 PHOTO HEAD

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Advanced packaging like Fan Out (FO) and System in Package (SiP) is becoming more of a standard to continue the systems size down of small form factor advanced electronics devices, such as mobile phones and smart watches.
Direct imaging solution for Fan Out Wafer Level Packaging (FOWLP) and Fan Out Panel Level Packaging (FOPLP) and other back end semiconductor applications will enable optimisation for the manufacturing process compared to conventional steppers.
IN advanced packaging, steppers obviously has limitations in local image warping based on the dies actual XY position and rotation.

After registration of the fiducials (dies) position, the LLS will in real time, while printing, warp the image such that the fan out signal lines is optimised between the dies and the substrate routing. Accurate local registration and LLS real time local image warping will enable to route more efficient,

with a higher density of signal lines, in the channel between dies pads. This will enable a system design with a smaller footprint which can enable better cooling (battery lifetime before charge is needed.) and of course a smaller footprint as such.

The LLS 2500 is a new Photo head in our LLS product line that will print 2 um Line space both on wafer with liquid resist and on PCB with dry resist.
Application must be tested and optimised but initial testing shows nice printing results in resists up to 12 um height.

Please contact us for further information.